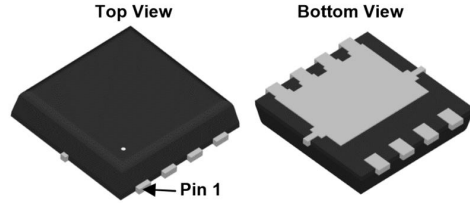
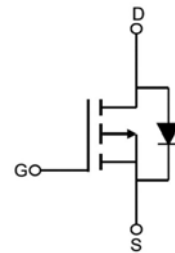
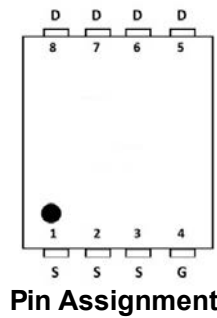


Features

- -40V, -40A
 $R_{DS(ON)}$ Typ = 7.7m Ω @ $V_{GS} = -10V$
 $R_{DS(ON)}$ Typ = 10.7m Ω @ $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free


PDFN3.3x3.3-8L

Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management

Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	-40	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	-40
		$T_C = 100^\circ C$	-24
I_{DM}	Pulsed Drain Current ⁽¹⁾	-160	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	121	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	28
$R_{\theta JC}$	Thermal Resistance, Junction to Case	4.5	$^\circ C/W$
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ C$

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	-40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -40\text{V}, V_{GS} = 0\text{V}$	-	-	-1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1.1	-1.6	-2.2	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = -10\text{V}, I_D = -20\text{A}$	-	7.7	10	m Ω
		$V_{GS} = -4.5\text{V}, I_D = -15\text{A}$	-	10.7	14.2	m Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = -20\text{V},$ $f = 1\text{MHz}$	-	2653	-	pF
C_{oss}	Output Capacitance		-	324	-	pF
C_{rss}	Reverse Transfer Capacitance		-	257	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } -10\text{V}$ $V_{DS} = -20\text{V}, I_D = -20\text{A}$	-	59	-	nC
Q_{gs}	Gate Source Charge		-	7.2	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	14.7	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn On DelayTime	$V_{GS} = -10\text{V}, V_{DD} = -20\text{V}$ $I_D = -20\text{A}, R_{GEN} = 3\Omega$	-	12.5	-	ns
t_r	Turn-On Rise Time		-	18	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	50	-	ns
t_f	Turn-Off Fall Time		-	28	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-40	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-160	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = -5\text{A}$	-	-	-1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$I_F = -20\text{A}, di/dt = 100\text{A}/\mu\text{s}$	-	40	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	43	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = -20\text{V}$, $V_G = -10\text{V}$, $R_G = 25\text{ohm}$, $L = 0.5\text{mH}$, $I_{AS} = -22\text{A}$
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

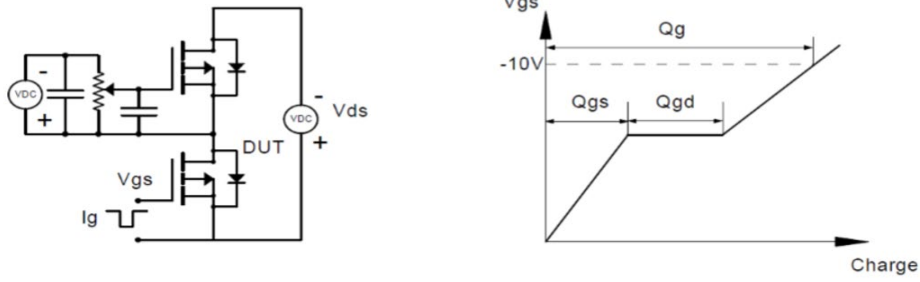


Figure 1: Gate Charge Test Circuit & Waveform

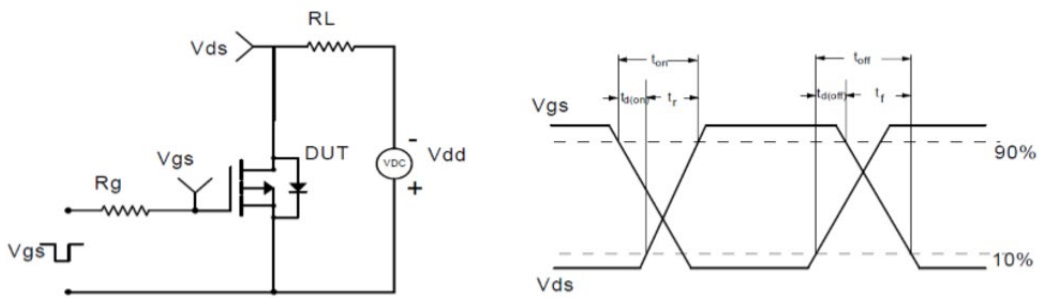


Figure 2: Resistive Switching Test Circuit & Waveform

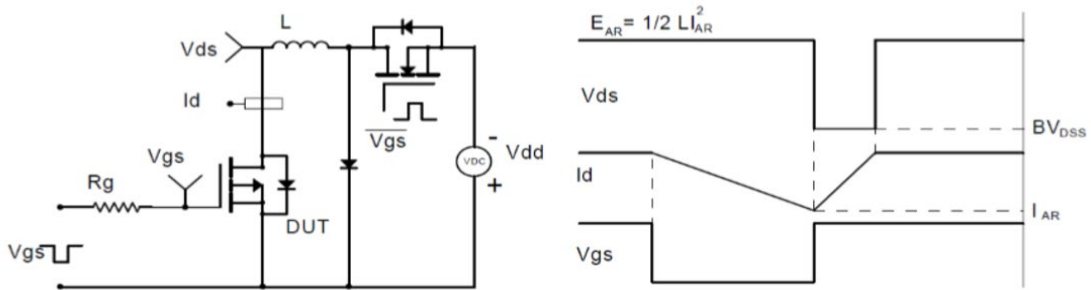


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

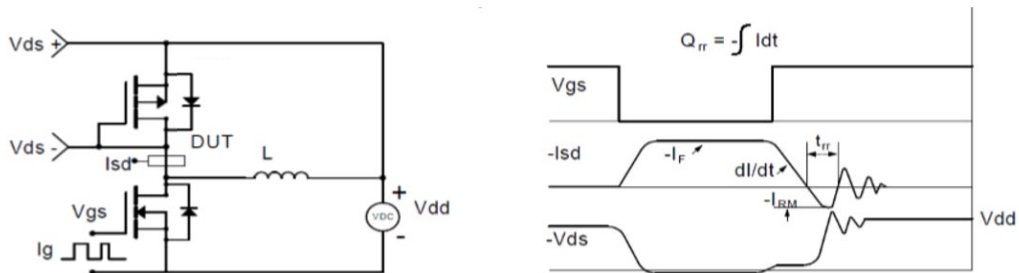
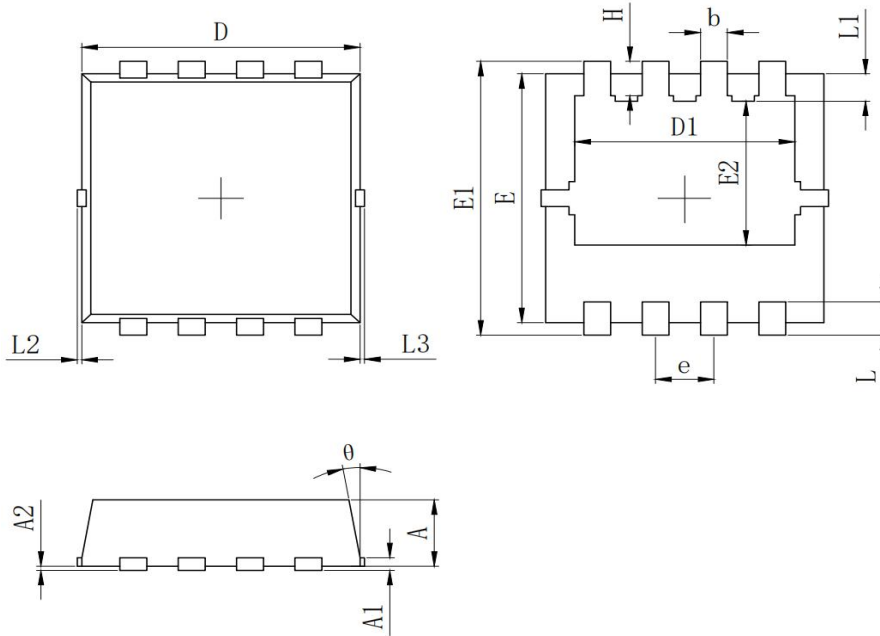


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN3.3x3.3-8L)



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.700	0.800	0.900
A1	0.152 REF.		
A2	0°0.05		
D	3.000	3.100	3.200
D1	2.300	2.450	2.600
E	2.900	3.000	3.100
E1	3.150	3.300	3.450
E2	1.535	1.735	1.935
b	0.200	0.300	0.400
e	0.550	0.650	0.750
L	0.300	0.400	0.500
L1	0.180	0.330	0.480
L2	0°0.100		
L3	0°0.100		
H	0.315	0.415	0.515
θ	8°	10°	12°